

Claim Amended Approved
and OK to enter
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Serial No. 10/706,576

16. (Original) The method of claim 15, further comprising electrically connecting bond pads of the another first-level semiconductor device to corresponding bond pads of the third-level semiconductor device.

17. (Original) The method of claim 15, further comprising electrically connecting bond pads of the third-level semiconductor device to corresponding conductors on the lower surface of the substrate.

18. (Currently amended) A method for assembling semiconductor device components, comprising:
providing an interposer with a substantially planar, substantially rigid substrate and a receptacle formed substantially through the substrate;
positioning a first semiconductor device over a first surface of the interposer, at least one bond pad of the first semiconductor device being exposed to the receptacle;
positioning a second semiconductor device over a second surface of the interposer, at least one bond pad of the second semiconductor device being exposed to the receptacle; and
electrically connecting the at least one bond pad of the first and second semiconductor devices through the receptacle; and
electrically connecting at least the first semiconductor device to the interposer, at least a laterally extending portion of one conductive element carried by a surface of the first semiconductor ~~device~~ device, also facilitating electrical connection of the second semiconductor device to the interposer upon electrically connecting the at least the first semiconductor device thereto.

19. (Previously presented) The method of claim 18, wherein electrically connecting includes securing a conductive structure to the at least one bond pad of the first semiconductor device or to the at least one bond pad of the second semiconductor device.